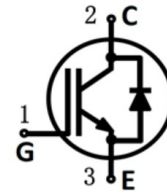


HCKD5N65AM2 is a **650V5A** IGBT discrete with high speed soft switching of Trench Field stop technology. The product with a anti-parallel diode, has the characteristics of low V_{CESAT} , high junction temperature and strong robustness. It is very suitable for products with motor and fans driver.

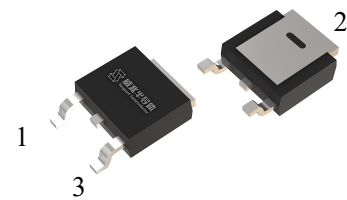
■ Features

- CoolWatt® II Trench-FS technology
- Low V_{CESAT}
- Low switching losses
- With anti-parallel fast recovery diode
- Positive temperature coefficient
- High reliability



■ Applications

- Motor driver
- Fans driver
- Refrigerator etc Appliance application



TO-252

Part ID	$V_{CE}(V)$	$I_{CNOM}(A)$	$V_{CESAT@25^{\circ}C}(V)$	Package	Marking
HCKD5N65AM2	650	5	1.45	TO-252	K5M652

■ Maximum Rated Values

Symbol	Parameter	Condition	Value	Unit
V_{CES}	Collector-emitter voltage	$T_{vj}=25^{\circ}C$	650	V
I_C	DC collector current	$T_C = 25^{\circ}C$	10	A
		$T_C = 100^{\circ}C$	5	
I_{Cpuls}	Pulse collector current	$T_{vj} \leq 150^{\circ}C$	15	A
V_{RRM}	Repetitive peak reverse voltage	$T_{vj}=25^{\circ}C$	650	V
I_F	Diode continuous forward current	$T_C = 25^{\circ}C$	10	A
		$T_C = 100^{\circ}C$	5	
I_{Fpuls}	Diode pulse current	$T_{vj} \leq 150^{\circ}C$	15	A
V_{GE}	Gate-emitter voltage	$T_{vj}=25^{\circ}C$	± 20	V
		Transient ($t_p \leq 10\mu S, D < 0.01$)	± 30	

t_{sc}	Short circuit withstand time	$V_{CC} \leq 400V, R_g = 51 \Omega, V_{GE} = 0/15V$	5	μs
I_{SC}	Short current	$V_{CC} \leq 400V, R_g = 51 \Omega, V_{GE} = 0/15V$	48	A
P_{tot}	Power dissipation	$T_C = 25^\circ C$	69	W
T_{vj}	Operating junction temperature		-40~+150	$^\circ C$
T_{stg}	Storage temperature		-50~+150	$^\circ C$

■ Thermal Characteristic

Symbol	Parameter	Maximum	Unit
$R_{thJC-IGBT}$	IGBT thermal resistance junction-case	1.80	K/W
$R_{thJC-FRD}$	FRD thermal resistance junction-case	4.50	K/W
R_{thJA}	Thermal resistance junction-ambient	55	K/W

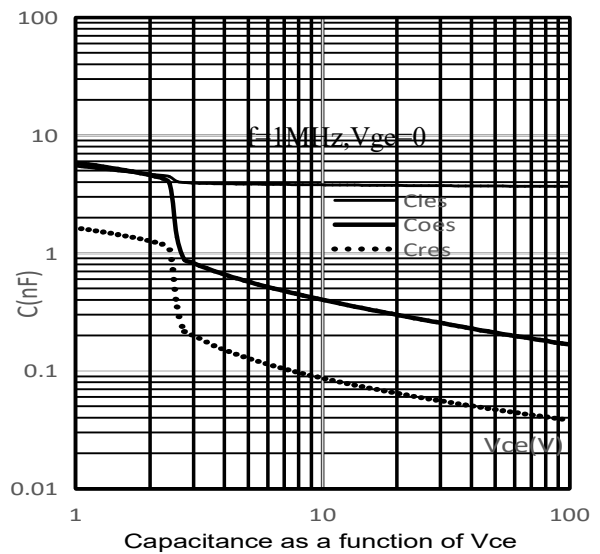
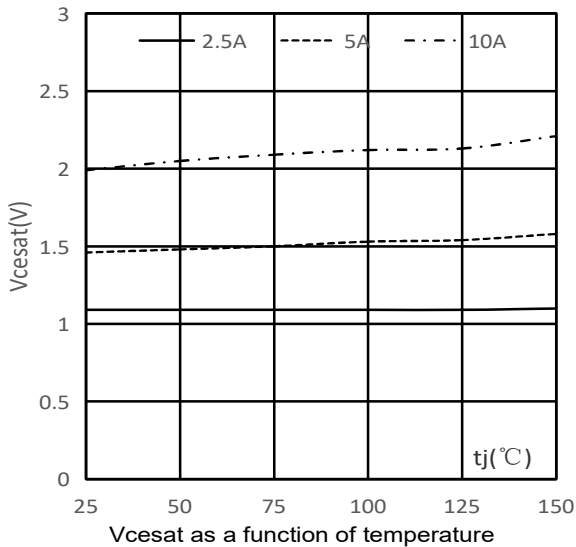
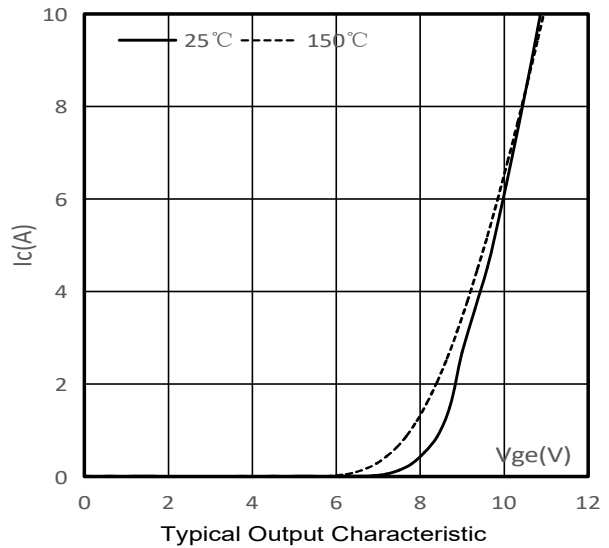
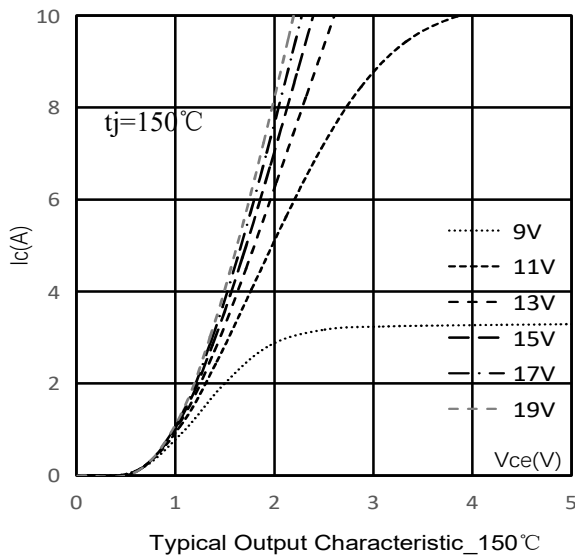
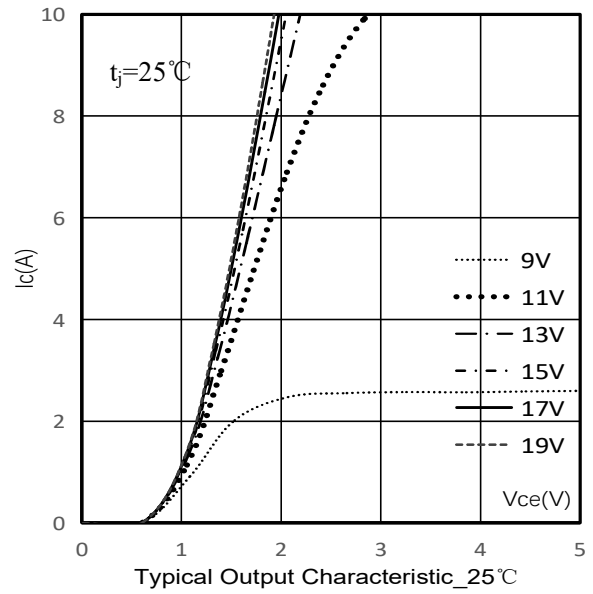
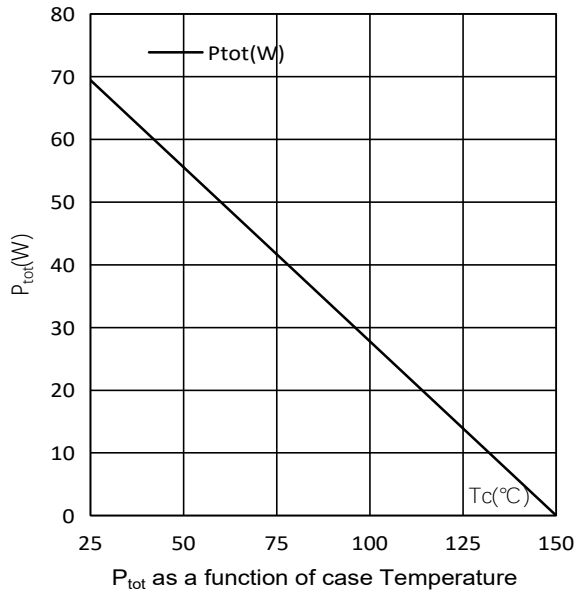
■ Electrical Characteristic

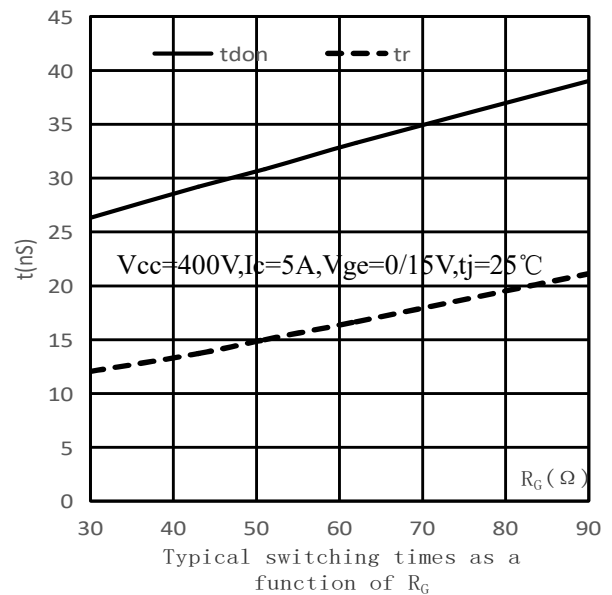
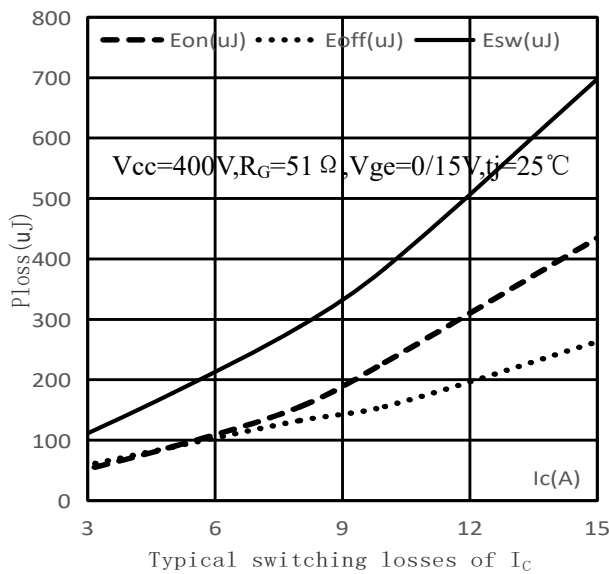
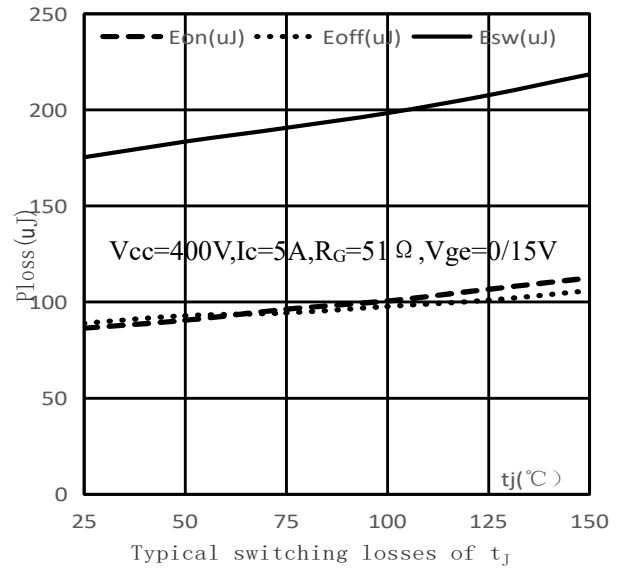
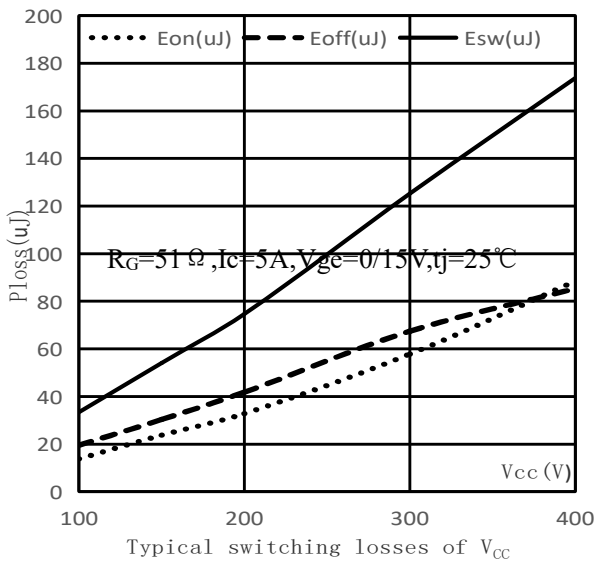
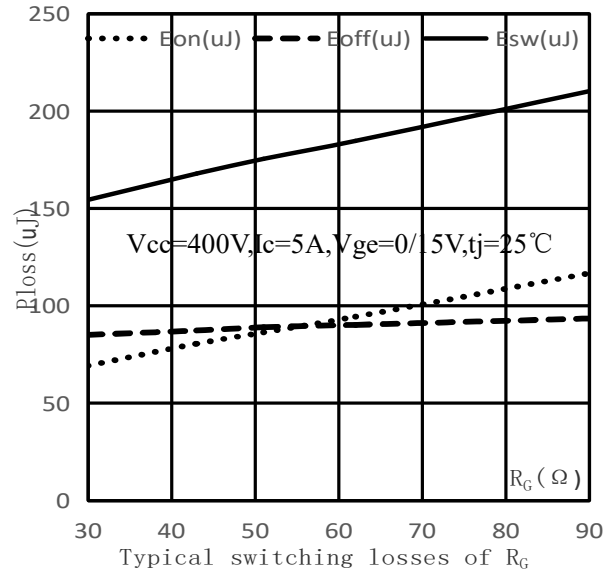
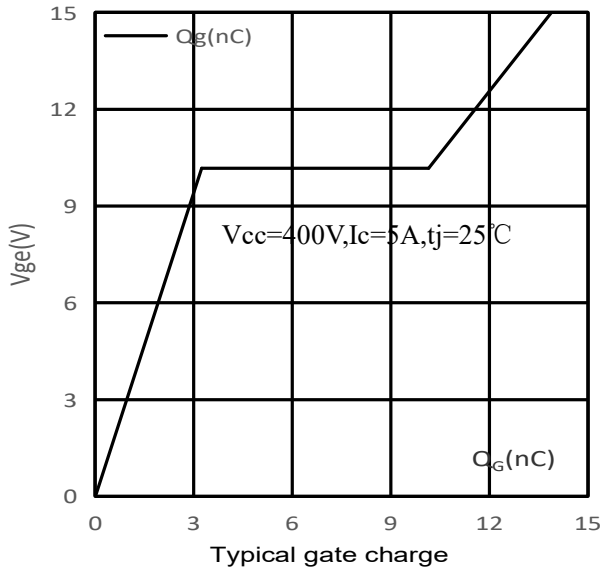
Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0V,$ $I_C = 0.25mA, T_{vj} = 25^\circ C$	650	—	—	V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15V, I_C = 5A, T_{vj} = 25^\circ C$ $T_{vj} = 150^\circ C$	—	1.45	1.85	
$V_{GE(th)}$	Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_C = 1.5mA, T_{vj} = 25^\circ C$	5.80	6.35	6.80	
V_F	Diode forward voltage	$V_{GE} = 0V, I_F = 5A, T_{vj} = 25^\circ C$ $T_{vj} = 150^\circ C$	—	1.75	2.05	
I_{GES}	Zero collector voltage gate current	$V_{GE} = 30V, V_{CE} = 0V$	—	—	200	nA
I_{CES}	Zero gate voltage collector current	$V_{CE} = 650V, V_{GE} = 0V, T_{vj} = 25^\circ C$ $T_{vj} = 150^\circ C$	—	—	0.20	mA
			—	—	0.50	
R_{Gin}	Integrated gate resistor	—	—	0	—	Ω
C_{ies}	Input capacitance	$V_{GE} = 0V, V_{CE} = 30V,$ $f = 1MHz, T_{vj} = 25^\circ C$	—	379	—	pF
C_{oes}	Output capacitance		—	26.1	—	
C_{res}	Reverse transfer capacitance		—	5.61	—	
Q_g	Gate charge	$V_{GE} = 0/15V, V_{CC} = 400V, I_C = 5A,$ $T_{vj} = 25^\circ C$	—	12.5	—	nC
Q_{ge}	Gate-emitter charge		—	3.39	—	
Q_{gc}	Gate-collector charge		—	5.48	—	
$V_{GE(pl)}$	Gate-emitter plateau voltage	$I_C = 5A, V_{CE} = 520V,$ $V_{GE} = 0/15V, T_{vj} = 25^\circ C$	—	9.88	—	V

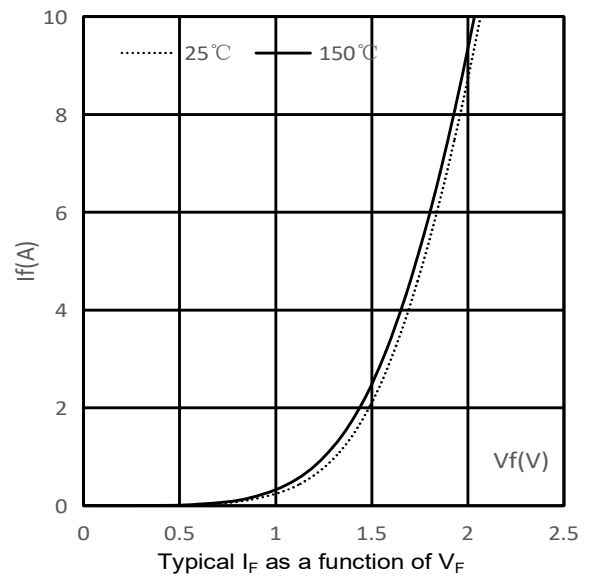
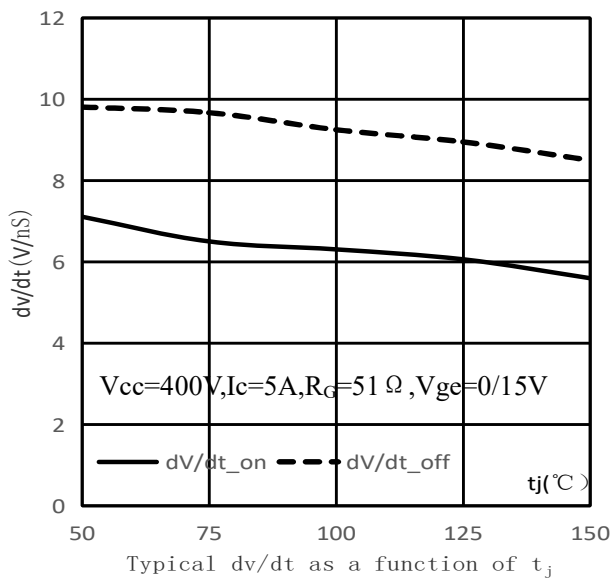
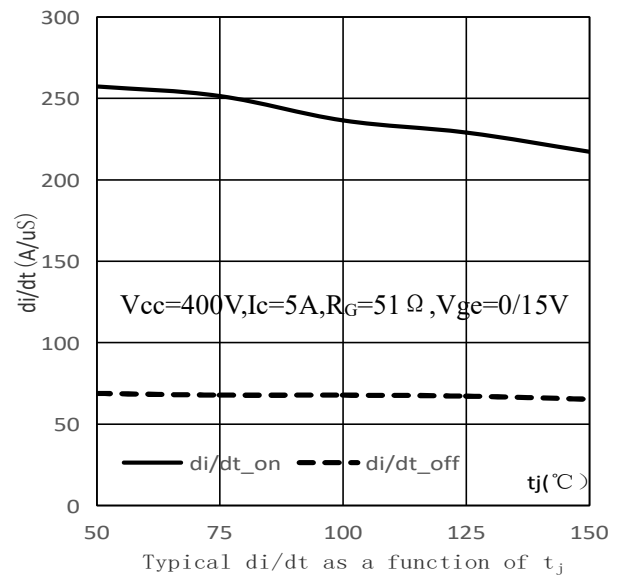
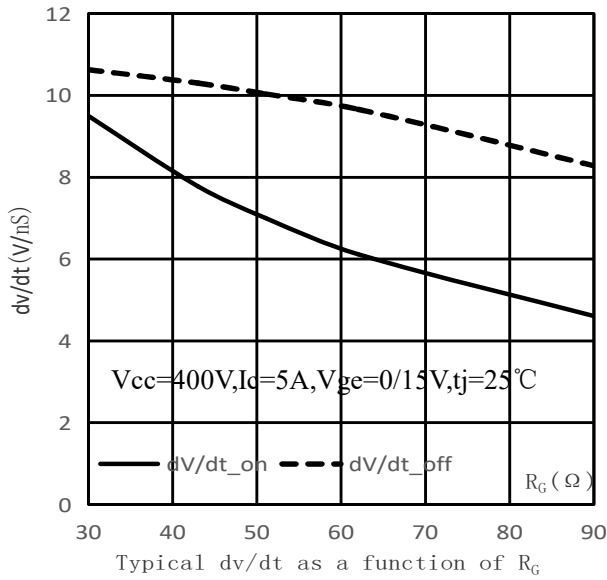
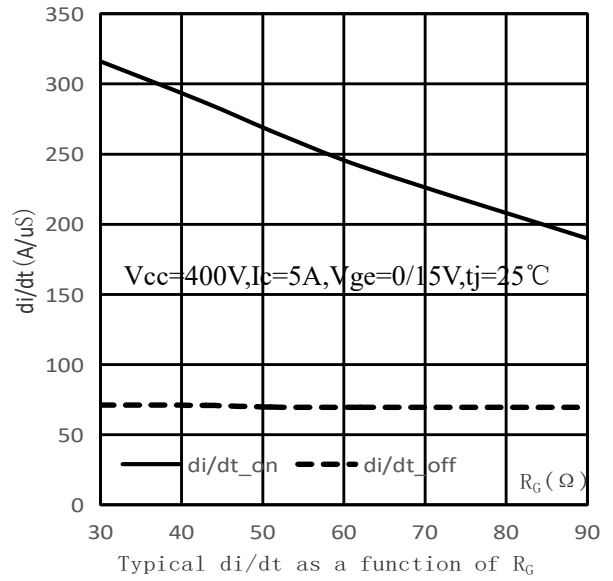
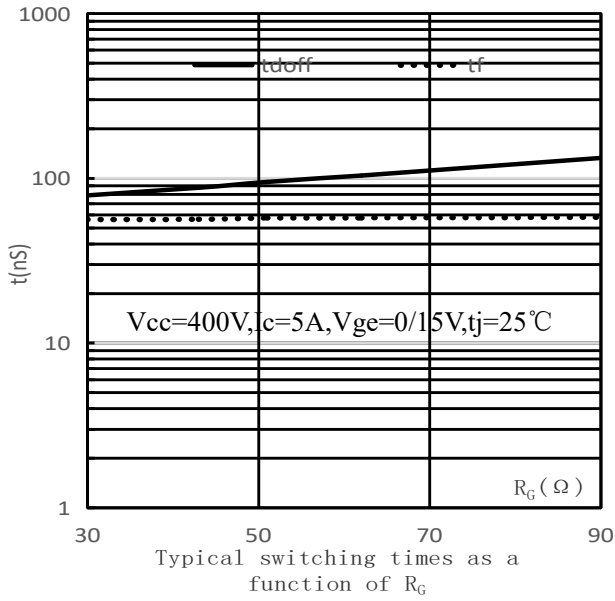
■ Dynamic Characteristic (With inductive load)

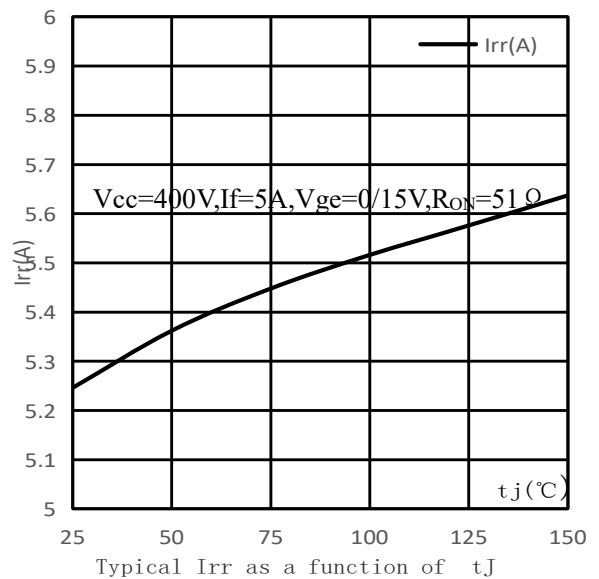
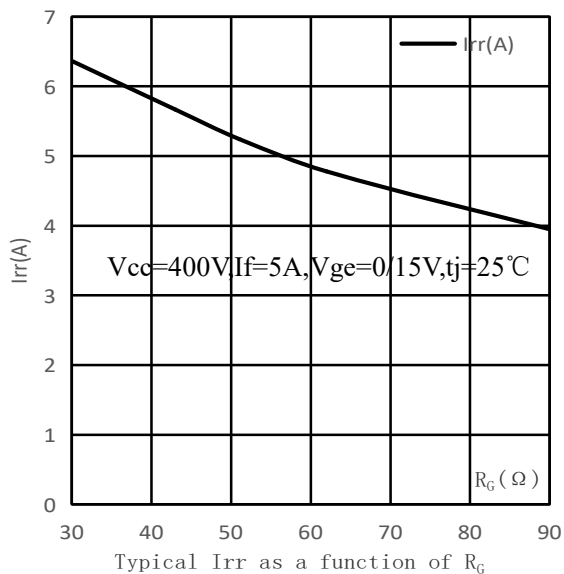
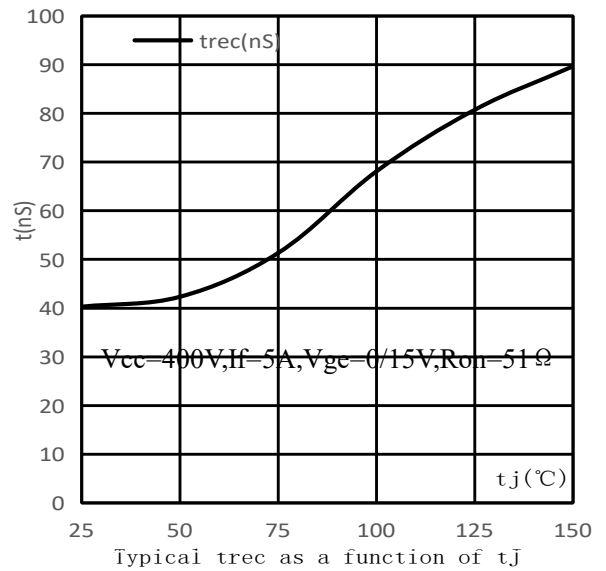
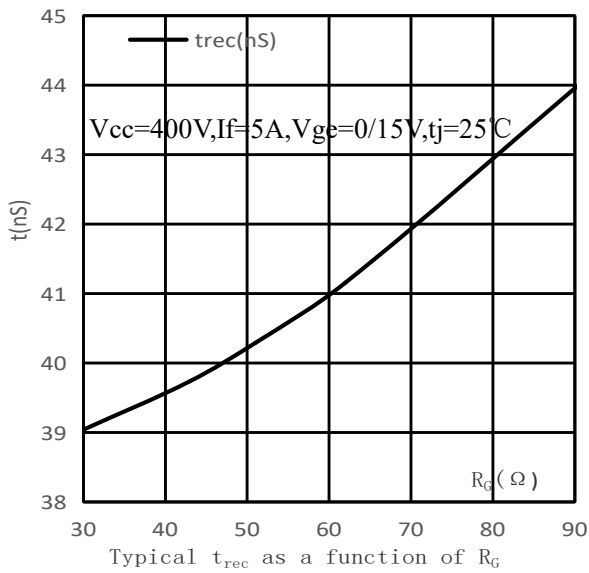
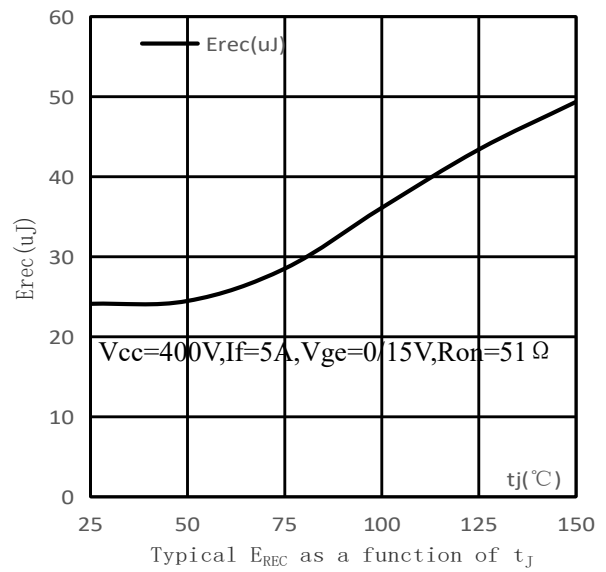
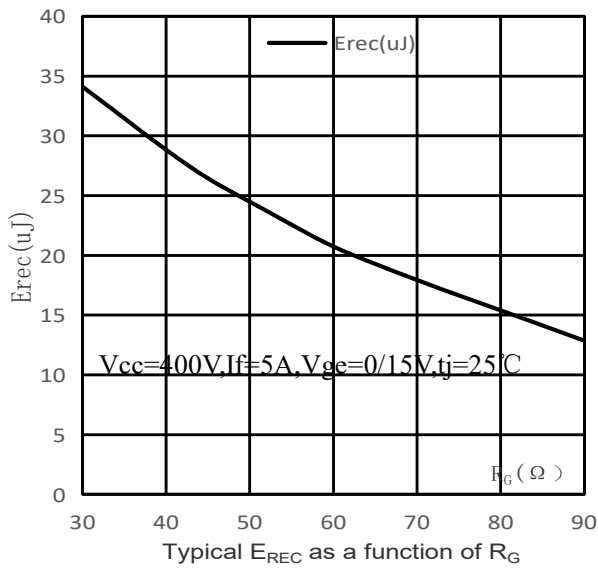
Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
IGBT Characteristic_25°C :						
$T_{d(on)}$	Turn-on delay time	$V_{CC}=400V, I_c=5A,$ $R_{on}=51\ \Omega, R_{off}=51\ \Omega,$ $C_{ge}=0nF, V_{GE}=0/15V,$ $L_{load}=500uH, T_{vj}=25^\circ C$	—	30.8	—	ns
T_r	Rise time		—	15.0	—	
$T_{d(off)}$	Turn-off delay time		—	95.2	—	
t_f	Fall time		—	57.4	—	
E_{on}	Turn-on energy		uJ	—	86.4	—
E_{off}	Turn-off energy			—	89.0	—
E_{total}	Total switch energy			—	175.4	—
IGBT Characteristic_150°C :						
$T_{d(on)}$	Turn-on delay time	$V_{CC}=400V, I_c=5A,$ $R_{on}=51\ \Omega, R_{off}=51\ \Omega,$ $C_{ge}=0nF, V_{GE}=0/15V,$ $L_{load}=500uH, T_{vj}=150^\circ C$	—	29.0	—	ns
T_r	Rise time		—	18.4	—	
$T_{d(off)}$	Turn-off delay time		—	106	—	
t_f	Fall time		—	61.3	—	
E_{on}	Turn-on energy		uJ	—	113	—
E_{off}	Turn-off energy			—	106	—
E_{total}	Total switch energy			—	219	—
Diode Characteristic_25°C :						
E_{rec}	Reverse recovery energy	$I_F=5A, V_R=400V,$ $V_{GE}=0/15V, R_{ON}=51\ \Omega, T_{vj}=25^\circ C$	—	24.1	—	uJ
t_{rr}	Diode reverse recovery time		—	40.3	—	nS
Q_{rr}	Diode reverse recovery charge		—	118	—	nC
I_{rrm}	Diode peak reverse recovery current		—	5.25	—	A
di_{rr}/dt	Diode peak rate of fall of reverse Recovery current during t_{rr}		—	259	—	A/uS
Diode Characteristic_150°C :						
E_{rec}	Reverse recovery energy	$I_F=5A, V_R=400V, V_{GE}=0/15V,$ $R_{ON}=51\ \Omega, T_{vj}=150^\circ C$	—	49.4	—	uJ
t_{rr}	Diode reverse recovery time		—	89.7	—	nS
Q_{rr}	Diode reverse recovery charge		—	218	—	nC
I_{rrm}	Diode peak reverse recovery current		—	5.64	—	A
di_{rr}/dt	Diode peak rate of fall of reverse Recovery current during t_{rr}		—	227	—	A/uS

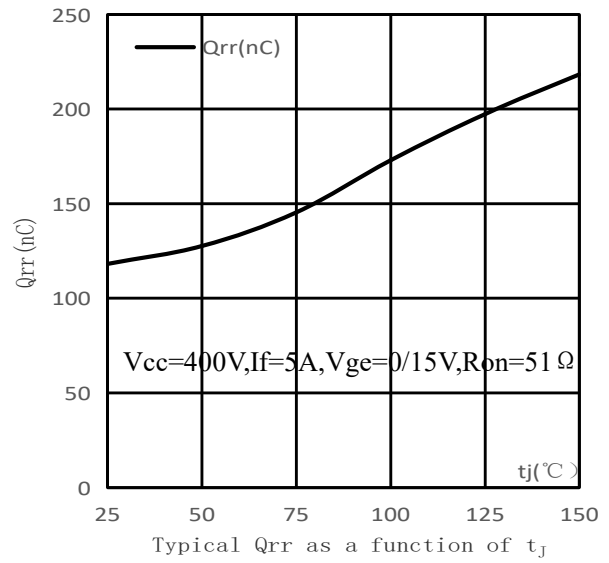
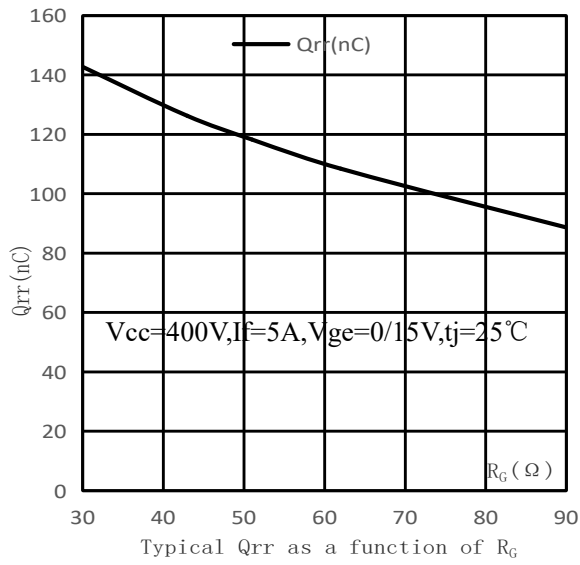
Characteristic Curve



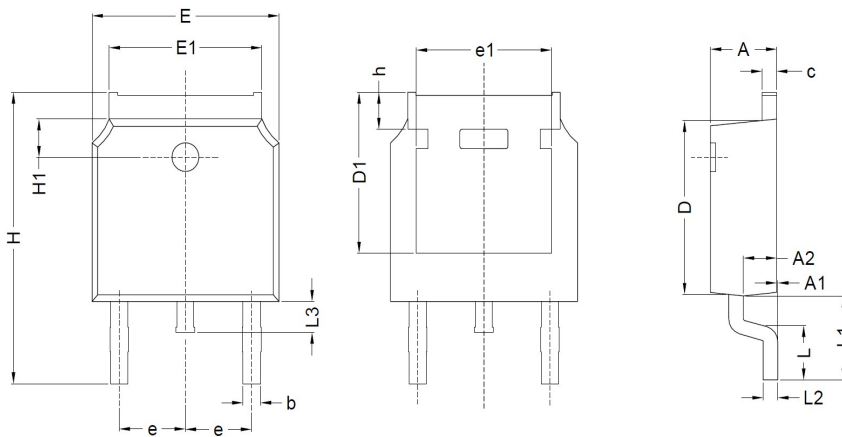








TO-252 Package Outline Data



Unit:mm

Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	2.20	2.30	2.40
A1	--	--	0.20
A2	0.97	1.02	1.17
b	0.60	--	0.90
c	0.43	--	0.61
D	5.98	6.10	6.22
D1	5.15	5.25	5.35
E	6.40	6.60	6.73
E1	5.18	5.33	5.49
e	2.286 BSC		
e1	4.63	--	4.85
H	9.40	10.00	10.50
H1	1.50	--	1.95
h	0.88	--	1.35
L	1.38	1.50	1.75
L1	2.90 REF		
L2	0.51 BSC		
L3	0.50	--	1.00